·WYUNDAI

HY51V18165B Series

1M × 16-bit CMOS DRAM with Burst EDO

PRELIMINARY

DESCRIPTION

The HY51V18165B is the new generation and fast dynamic RAM organized 1,048,576 x 16-bit. The HY51V118165B utilized Hyundai's CMOS silicon gate process technology as well as advenced circuit techniques to prove wide operating margin to the users. This device can be packaged in industry-standard 42/42 plastic SOJ, 44/50 TSOP-II and Reverse TSOP-II.

The HY51V18165B is a burst access DRAM in which all READ and WRITE cycles occur in bursts of four. The burst wrap around on a eight byte boundary. This means only the two least significant bits of the CAS address

are modified internally to produce each address of the burst sequence.

The burst type, interleave or linear, is determined by excuting a WCBR cycle with address A0 set to either HIGH or LOW. A0 LOW will program the device to excute linear bursts, A0 HIGH will program the bursts to be interleave. For future compatability it is strongly recommended that the information 0010 000X (where x=A0) is supplied on addresses A7-A0 during the WCBR cycle. The WCBR cycle must be followed by a RAS-only or CBR to exit programming mode.

FEATURES

 Low power dissipation Max. CMOS standby 0.83mW Max. TTL standby 0.33mW Max. operating

Speed	Power1	Power2
50	576mW	648mW
60	540mW	612mW
70	504mW	576mW

NOTE

Power1: Closed Row Burst Read/Write Power2: Open Row Burst Read/Write

- Single power supply of 3.3V±5%
- · All inputs and outputs are LVTTL compatible with 5V input/out put tolerance
- · Fast access and cycle time

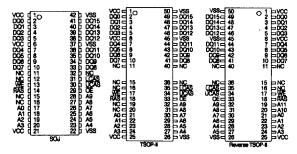
Speed	tRAC	tCAC	tPC
50	52ns	10ns	15ns
60	60ns	11.6ns	16.6ns
70	70ns	15ns	20ns

- Burst EDO mode operation
- Burt order, interleave or linear, programmed by excuting WCBR cycle after initialization
- Industry-stardard x 16 pinout and package
- CAS-before-RAS, RAS-only refresh capability
- 1024 refresh cycles /16ms
- Four cycle EDO burst access

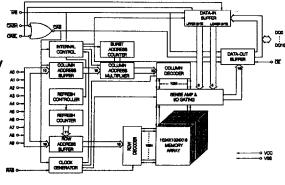
PIN DESCRIPTION

RAS	Row Address Strobe
LCAS, UCAS	Column Address Strobe
WE	Write Enable
ŌĒ	Output Enable
A0 - A9	Address Input
DQ0-DQ15	Data Input/Output
Vcc	Power (+3.3V)
Vss	Ground

PIN CONNECTION



BLOCK DIAGRAM



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EDO BURST MODE TRUTH TABLE

PRESENT-	RESULTING STATE	RAS	CAS	WE	OE	ADDRESS		DATA	
STATE	RESULTING STATE	RAS	CAS	***	UE	Row	Column	DQ	
Any	Idle	L → H	Н	Х	Х	X	X	High-Z	
Idle	Row Open	H → L	Н	Х	Х	Row	Х	High-Z	
Idle	CBR REFRESH	H → L	L	Н	Х	Х	Х	High-Z	
Row Open	RAS-only REFRESH	H→L→H	Н	X	Х	Row	X	High-Z	
Row Open	READ burst	L	H→L	Н	L	X	Col	Data-Out	
Row Open	WRITE burst	L	H→L	L	X	Х	Col	Data-In	
READ burst	TERMINATE READ burst	L	Н	H→L	X	X	Х	High-Z	
WRITE burst	TERMINATE WRITE burst	L	Н	L→H	Х	Х	Х	High-Z	
ldle	PROGRAM burst type	H → L	L	L	X	A0	Х	High-Z	
PROGRAM	EXIT PROGRAM MODE	H → L	L	Н	Х	Х	Х	High-Z	
PROGRAM	EXIT PROGRAM MODE	H→L→H	Н	Х	Х	Row	Х	High-Z	

Note:

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INTERLEAVE BURST SEQUENCE TABLE

OPERATION	ADDRESSES USED						
OFERATION	A9 - A2	A1	A0				
First access, register external CAS address	A9 - A2	A1	A0				
Second access (first burst address)	registered A9 - A2	registered A1	registered A0				
Third access (second burst address)	registered A9 - A2	registered A1	registered A0				
Fourth access (third burst address)	registered A9 - A2	registered A1	registered AO				

INTERLEAVE BURST ADDRESS TABLE

FIRST ADDRESS	SECOND ADDRESS	THIRD ADDRESS	FOURTH ADDRESS
XX00	XX01	XX10	XX11
XX01	XX00	XX11	XX10
XX10	XX11	XX00	XX01
XX11	XX10	XX01	XX00

LINEAR BURST ADDRESS TABLE

FIRST ADDRESS	SECOND ADDRESS	THIRD ADDRESS	FOURTH ADDRESS
XX00	XX01	XX10	XX11
XX01	XX10	XX11	XX00
XX10	XX11	XX00	XX01
XX11	XX00	XX01	XX10

A WCBR cycle determines the burst sequence. A0=LOW sets burst sequence to linear, A0=HIGH set the
burst sequence to interleave, A8 through A9 are don't care. A7-A0 should contain the sequence (0010
000X where X=A0) to ensure future compatability. A refresh cycle (RAS-only or CBR) must follow WCBR
cycle to exit the programming mode.

ABSOLUTE MAXIMUM RATING

SYMBOL	PARAMETER	RATING	UNIT
TA	Ambient Temperature	0 to 70	℃
TSTG	Storage Temperature	-55 to 150	℃
Vin, Vout	Voltage on Any Pin Relative to Vss	-0.1 to 5.5	٧
los	Short Circuit Output Current	50	mA
Po	Power Dissipation	- 1.1	W

NOTE: Operation at or above Absolute Maximum Ratings can adversely affect device reliability.

RECOMMENDED DC OPERATING CONDITIONS

 $(TA = 0^{\circ}C \text{ to } 70^{\circ}C)$

SYMBOL	PARAMETER	MIN.	MAX.	UNIT	NOTE
Vcc	Power Supply Voltage	3.13	3.47	V	
ViH	Input High Voltage	2.0	5.5	V	2
ViL	Input Low Voltage	-1.0	0.8	V	2

NOTE: All Voltage are referenced to Vss.

DC CHARACTERISTICS

(TA=0°C to 70°C, Vcc=3.3V±10%, Vss=0V, unless otherwise noted.)

SYMBOL	PARAMETER	TEST CONDITIONS	SPEED/ POWER	MIN.	MAX.	UNIT	NOTE
lu	Input Leakage Current	OV ≤ VIN ≤ 5.5V		-2	2	μΑ	
	(Any Input Pins)	All other pins not under test =	All other pins not under test = OV				
llo	Output Leakage Current	OV ≤ Vout ≤ 5.5V		-10	10	μА	
	(High impedance State)	RAS & CAS at VIH			· .		
ICC1	Vcc Supply Current,	RAS & CAS at VIH (min.),		-	2	mA	
	TTL Standby	other Inputs ≥ Vss					
ICC2	Vcc Supply Current, CMOS Standby	RAS & CAS ≥ Vcc-0.2V		-	0.5	mA	
ICC3	Vcc Supply Current,	tPC = tPC (min): 50% duty	50	-	160	mA	5
	Operating ; Closed Row	cycle on RAS: Open Row, 4	60	-	150		į
	Burst Read / Write	Cycle Burst, Close Row	70	-	140		
ICC4	Vcc Supply Current,	tPC = tPC (min): Alternating	50	-	180	mA	5
	Operating : Open Row	4 cycles inactivity	60	-	170	l	
	Burst Read / Write		70	-	160		
ICC5	Vcc Supply Current,	tPC = tPC (min.)	50	-	200	mA	4
	RAS-only refresh		60	-	190		
			70	_	180		
ICC6	Vcc Supply Current,	tRC = tRC (min.)	50	-	200	mA	4,6
	CAS-before- RAS refresh		60	-	190	ł	
			70	-	180		
Vol	Output Low Voltage	IOL = 2mA			0.4	V	
Voн	Output High Voltage	Iон = -2mA		2.4	-	V	

CAPACITANCE

(TA=25°C, VCC=3.3V±10%, Vss=0V, f=1MHz, unless otherwise noted.)

SYMBOL	PARAMETER	MIN	MAX	UNIT	NOTE
Cit	Input Capacitance : Address		5	pF	3
CI2	Input Capacitance : RAS		6	pF	3
Сіз	Input Capacitance : CAS, WE, OE		5	рF	3
Cio	Data Input/Output Capacitance : DQ		7	pF	3

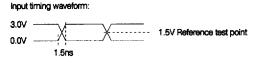
AC CHARACTERISTICS

(TA=0°C to 70°C, Vcc=3.3V \pm 5%, Vss=0V, unless otherwise noted.) NOTE: 7, 8, 9, 10, 11

		MBOL PARAMETER	HY51V18165BJC/TC/RC							
#	SYMBOL			50	-60		-70		UNIT	NOTE
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
1	tPC	Burst EDO Cycle Time	15	-	16.6	-	20	-	กร	
2	tRAC	Access Time from RAS	-	50	- "	60	-	70	ns	
3	tCAC	Access Time from CAS	-	10	-	11.6	-	15	ns	
4	tAA	Access Time from Column-Address	-	25	-	28.2	-	35	ns	12
5	tOEA	Output Enable Access Time	-	10	-	12	-	15	ns	
6	tCOH	Data Hold Time from CAS Low	3	-	3	-	3	-	ns	
7	tRAS	RAS Pulse Width	50	125K	60	125K	70	125K	ns	
8	tRP	RAS Precharge Time	30	-	40	-	50	-	ns	
9	tRSH	RAS Hold Time	0	-	0	-	0	-	ns	
10	tCAS	CAS Pulse Width	5	10K	5	10K	5	10K	ns	
11	tCP	CAS Precharge Time	5	-	5	-	5	-	ns	1
12	tRCD1	RAS to CAS Delay Time	20	-	16.6	-	20	-	ns	
13	tRCD2	RAS to CAS Delay Time	40	-	46.6	-	55	-	ns	<u> </u>
14	tCRP	CAS to RAS Precharge Time	10	-	10	-	10	-	ns	
15	tASR	Row-Address Set-up Time	1.5	-	1.5	-	1.5	-	ns	
16	tRAH	Row-Address Hold Time	8.5	-	8.5	-	8.5	-	ns	<u> </u>
17	tASC	Column-Address Set-Up Time	1.5	-	1.5	-	1.5	-	ns	
18	tCAH	Column-Address Hold Time	8.5	-	8.5	-	8.5	-	ns	
19	tRCS	Read Command Set-Up Time	3	-	4	-	5	-	ns	
20	tRCH	Read Command Hold Time	5	-	5	-	5	-	ns	
21	tOEP	OE High Pulse Width	10	-	10	-	10	-	ns	
22	tOELZ	OE to Output Low-Z	3	-	3	-	3	-	ns	13
23	tOD	Output Disable	4	10	4	10	4	15	ns	13
24	tOES	Output Enable Set-Up (Only near CAS)	3	 	3	-	3	_	ns	
25	tOEH	Output Enable Hold (Only near CAS)	5	 	5	-	5	_	ns	
26	tCLZ	CAS to Output in Low-Z	3	 -	3	-	3	-	ns	13
27	tOFF	Output Buffer Turn-Off Delay	4	10	4	10	4	15	ns	13
28	tBTH	Burst Terminate Hold Time	3	<u> </u>	3	-	3	-	ns	
29	tBTHZ	Output disable from burst Terminate	7	13	7	13	7	13	ns	13,16
30	twcs	WE Command Set-Up Time	3	-	4	-	5	-	ns	1.01.0
31	tWCH	Write Command Hold Time	5	-	5	 -	5	-	ns	
32	twnz	WE to Output High-Z	4	10	4	10	4	15	ns	13,16
33	tTP	Burst Terminate Pulse Width	6	-	6	-	8	-	ns	14
34	tCRW	CAS Low to RAS High (Required Only for WRITE Only)	15	-	16.6	-	20	-	ns	
35	tD\$	Data-in Set-Up Time	0	-	0	-	0	-	กร	
36	tDH	Data-in Hold Time	5	-	5	-	5	-	ns	
37	t⊤	Transition Time (rise or fall)	1.5	50	1.5	50	1.5	50	ns	
38	tREF	Refresh Period (1024 Cycle)	-	16	-	16	-	16	ms	
39	tRPC	RAS to CAS Precharge Time	5	-	5	-	5	-	ns	
40	tRC	Random Read or Write cycle Time	90		110	-	130	-	ns	
41	tWRP	WE Set-Up Time (CBR or WCBR)	10	-	10	-	10	-	ns	
42	twrh	WE Hold Time (CBR or WCBR)	10	-	10	-	10	-	ns	
43	tCPN	CAS Precharge Time (CBR or WCBR)	10	-	10	-	10	-	ns	
44	tCSR	CAS Set-Up Time (CBR or WCBR)	10	-	10	-	10	-	ns	6
45	tCHR	CAS Hold Time (CBR or WCBR)	15	-	15	-	15	-	ns	6

NOTE:

- 1. All voltage referenced to Vss.
- Input Power-up: VIH ≤ +5.5V and Vcc ≤ +3,13V for t ≤ 200msec.
- 3. This parameter is sampled. Vcc=3.3V ± 5%: f=1 MHz
- 4. Icc is dependent on cycle rates.
- Icc is dependent on output loading and cycle rates. Specified values are obtained with minimum tPC and 50 percents duty cycle. The outputs are open.
- 6. Enables on-chip refresh and address counters.
- 7. Initialization consists of an initial pause of 100µs after power-up followed by eight RAS refresh cycles (RAS-only or CBR with WE HIGH). This sequence must be executed before proper device operation is assured. The eight RAS cycle wake-ups should be repeated any time the tREF refresh requirement is exceeded. A WCBR cycle must be executed to initalize the burst type, interleave or linear followed by a RAS-only or CBR refresh cycle.
- 8. AC characteristics assume tT=1.5ns.
- All output timings are referenced to 1.5V and all input timings are referenced to 1.5V, unless otherwise specified. Inputs must be driven to the appropriate voltage levels indicated by the corresponding timing diagrams when A.C. specifications are measured, as shown in Figure 1.
- 10.In addition to meeting the transition rate specification, all input signals must transit between VIH and VIH (or between VIL and VIH) in a monotonic manner.
- 11.NC pins are assumed to be left floating and are not tested for leakage.
- 12.tAA is a calculated specification which is the sum of tPC and tCAC.
- 13.Output loading is specified with CL=5pF as Figure 2. Transition is measured ± 200mV from steady state voltage. These parameters are sampled.
- 14.Applies only during burst termination operation.
- 15.AC output loading is specified with CL=50pF as in Figure 3. Figure 4. is shown for reference. Transition is measured at the 1.5V referenced level.
- 16. The latter of twHz or tBTHZ satisfied will place the DQ pins in the High-Z state.



Output timing waveform:

1.5V Reference test point

Fig. 1 TIMING SPECIFICATIONS

Fig. 3 AC TIMING OUTPUT LOAD EQUIVALENT

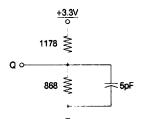


Fig. 2 HIGH-Z OUTPUT LOAD

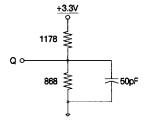
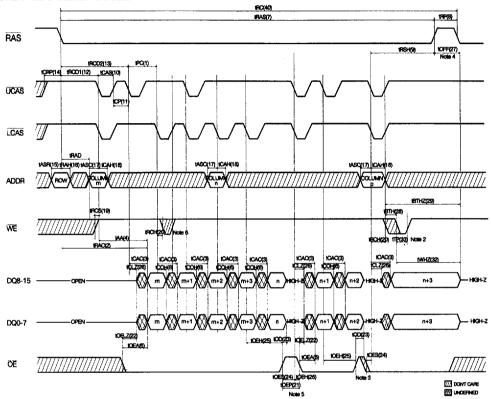


Fig. 4 OUTPUT LOAD EQUIVALENT

TIMING DIAGRAM





NOTE:

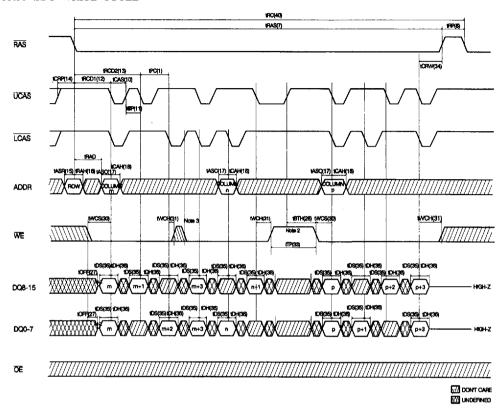
- 1. Both bytes are always output during READ operations.
 - UCAS and/or LCAS control both bytes on READs. UCAS and LCAS must transition within 2ns of each other. UCAS and LCAS must be HIGH coincident for 5ns.
 - All setup, hold, and access times are measured from the first CAS transitioning from HIGH to LOW on each READ cycle within the burst.
- 2. WE transitioning LOW will terminate the burst and reset the burst counter provided tTP and tBTH are satisfied.

 The DQs will be placed in the High-Z state once the latter of tWHZ or tBTHZ is satisfied.
- 3. When CAS is HIGH if OE transition HIGH during a burst READ cycle then transitions LOW, the outputs will remain in HIGH-Z until tctz after the next falling edge of CAS.
- 4. The combination of RAS and CAS HIGH close the row and tristate the bus. toff is measured from the last signal (RAS or CAS) that transitions HIGH.
- 5. Output enable (OE) is an asynchronous signal.

 The toes and toeh specifications are required only when Output enable transitions from active (LOW) to inactive (HIGH) either toes, before the falling edge of CAS or toeh, after the falling edge of CAS.

 When OE transitions HIGH after CAS transitions LOW, the DQ pins are placed in the High-Z state and will remain in the High-Z state until another CAS LOW transitions occurs, regardles of the state of OE.
- 6, WE transitioning LOW and returning HIGH prior to CAS going HIGH will not terminate the burst.

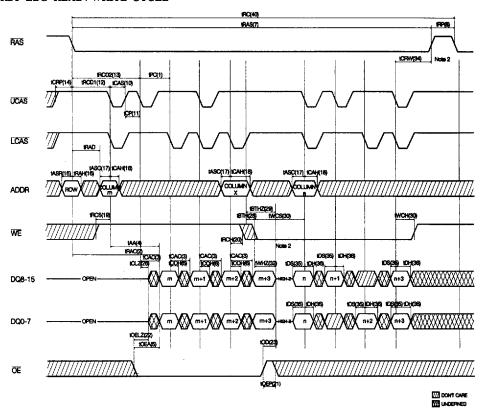
BURST EDO WRITE CYCLE



NOTE:

- LCAS and UCAS each control their respective bytes on WRITEs.
 Each must transition to write their respective byte.
 UCAS and UCAS must be HIGH coincident for 5ns.
 All setup and hold times are measured from the first CAS transitioning from HIGH to LOW on each WRITE cycle within the burst. The skew between UCAS and UCAS must not exceed 2ns.
- 2. WE transitioning HIGH will terminate the burst and reset the burst counter provided tTP and tBTH are satisfied.
- 3. WE transitioning HIGH and returning LOW prior to CAS going HIGH will not terminate the burst.

BURST EDO READ/WRITE CYCLE



NOTE:

1. Both bytes are always output during READ operations.

UCAS and/or LCAS control both bytes on READs UCAS and LCAS must transition within 2ns of each other. UCAS and LCAS must be HIGH coincident for 5ns.

All setup, hold, and access times are measured from the first $\overline{\text{CAS}}$ transitioning from HIGH to Low on each LOW on each cycle within the burst.

LCAS and UCAS each control their respective bytes on WRITEs.

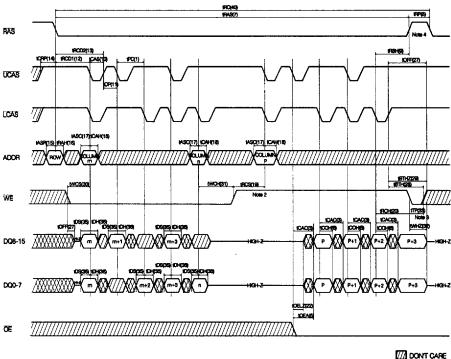
Each must transition to write their respective byte.

UCAS and LCAS must be HIGH coincident for 5ns.

All setup and hold times are measured from the first $\overline{\text{CAS}}$ transitioning from HIGH to LOW on each WRITE cycle within the burst. The skew between $\overline{\text{UCAS}}$ and $\overline{\text{LCAS}}$ must not exceed 2ns.

- 2. WE transitioning LOW will terminate the burst and reset the burst counter provided tTP and tBTH are satisfied. tTP is met by the READ burst being terminated by a WRITE burst. The DQs will be placed in the High-Z state once the latter of the tWHZ or tBTHZ is satisfied.
- 3. The combination of RAS and CAS HIGH close the row and place the DQs pins in the High-Z state.

BURST EDO WRITE/READ CYCL



DON'T CARE

NOTE:

1. LCAS and UCAS each control their respective bytes on WRITEs.

Each must transition to write their respective byte.

UCAS and LCAS must be HIGH coincident for 5ns.

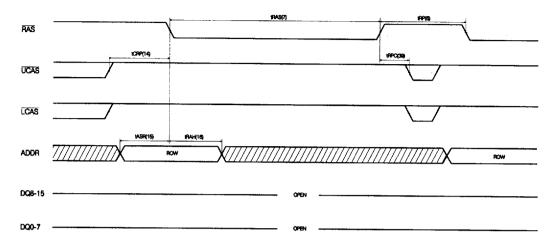
All setup and hold times are measured from the first CAS transitioning from HIGH to LOW on each WRITE cycle within the burst. The skew between UCAS and LCAS must not exceed 2ns. Both bytes are always output during READ operations.

UCAS and/or LCAS control both bytes on READs. UCAS and LCAS must transition within 2ns of each other. UCAS and LCAS must be HIGH coincident for 5ns.

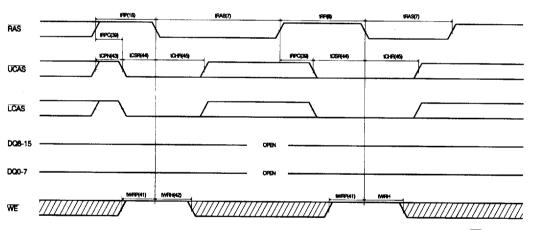
All setup, hold, and access times are measured from the first CAS transitioning from HIGH to LOW on each READ cycle within the burst.

- 2. WE transitioning HIGH will terminate the burst and reset the burst counter. The tBTH time is not required as it is satisfied by tRCS: tTP is met by the WRITE burst being terminated by a READ burst.
- WE transitioning LOW will terminate the burst and reset the burst counter provided tTP and tBTH are satisfied.
 The DQs will be placed in the High-Z state once the latter of tWHZ or tBTHZ is satisfied.
- The combination of RAS and CAS HIGH close the row and place the DQ pins in the High-Z state. toFF is measured from the last signal (RAS or CAS) that transitions HIGH.

RAS-ONLY REFRESH CYCLE

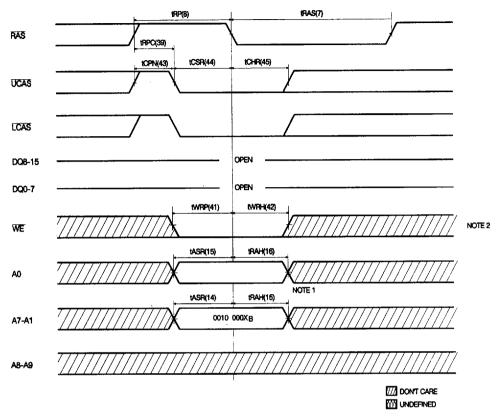


CBR REFRESH CYCLE



DON'T CARE **UNDEFINED**

WCBR PROGRAM CYCLE



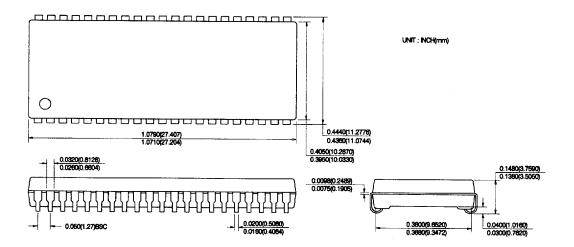
NOTE:

- 1. A0 LOW sets the burst sequence to linear bursts. A0 HIGH sets the burst sequence to interleave bursts. Addresses A8 through A9 are don't cares. Address A7-A1 should contain the state of (0010 000Xs where x=A0) to ensure future compatability. The burst sequence will remain set until the device power is interrupted or another WCBR cycle is executed.
- 2. A RAS-only or CBR refresh cycle must be executed after the WCBR cycle to exit the programming mode.

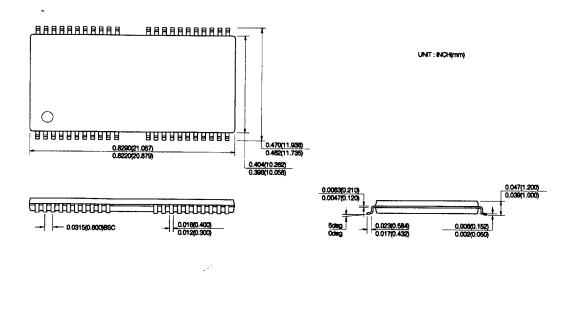
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PACKAGE INFORMATION

400 mil 42 pin Small Outline J-form Package (JC)



400 mil 44/50 pin Thin Small Outline Package (TC) (RC)



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ORDERING INFORMATION

PART NO	SPEED	POWER	PACKAGE
HY51V18165BJC	50/60/70		SOJ
HY51V18165BTC	50/60/70		TSOP-II
HY51V18165BRC	50/60/70		TSOP-II(R)